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(12) **United States Design Patent**  
**Nagaune**

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(54) **COOLING JACKET FOR SEMICONDUCTOR DEVICE**

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(73) Assignee: **Fuji Electric Co., Ltd.**, Kanagawa (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/406,390**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/179**

(58) **Field of Classification Search**  
USPC ..... D13/122, 179, 182; 165/80.2, 80.4,  
165/104.19; 361/702

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a cooling jacket for semiconductor device, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of front, top plan and right side of a cooling jacket for semiconductor device showing my new design;  
FIG. 2 is a perspective view of rear, bottom and left side thereof;  
FIG. 3 is a front view thereof;  
FIG. 4 is a rear view thereof;  
FIG. 5 is a top plan view thereof;  
FIG. 6 is a bottom view thereof;  
FIG. 7 is a left side view thereof;  
FIG. 8 is a right side view thereof; and,  
FIG. 9 is a cross-sectional view thereof taken along line 9-9 in FIG. 9 view.

**1 Claim, 7 Drawing Sheets**

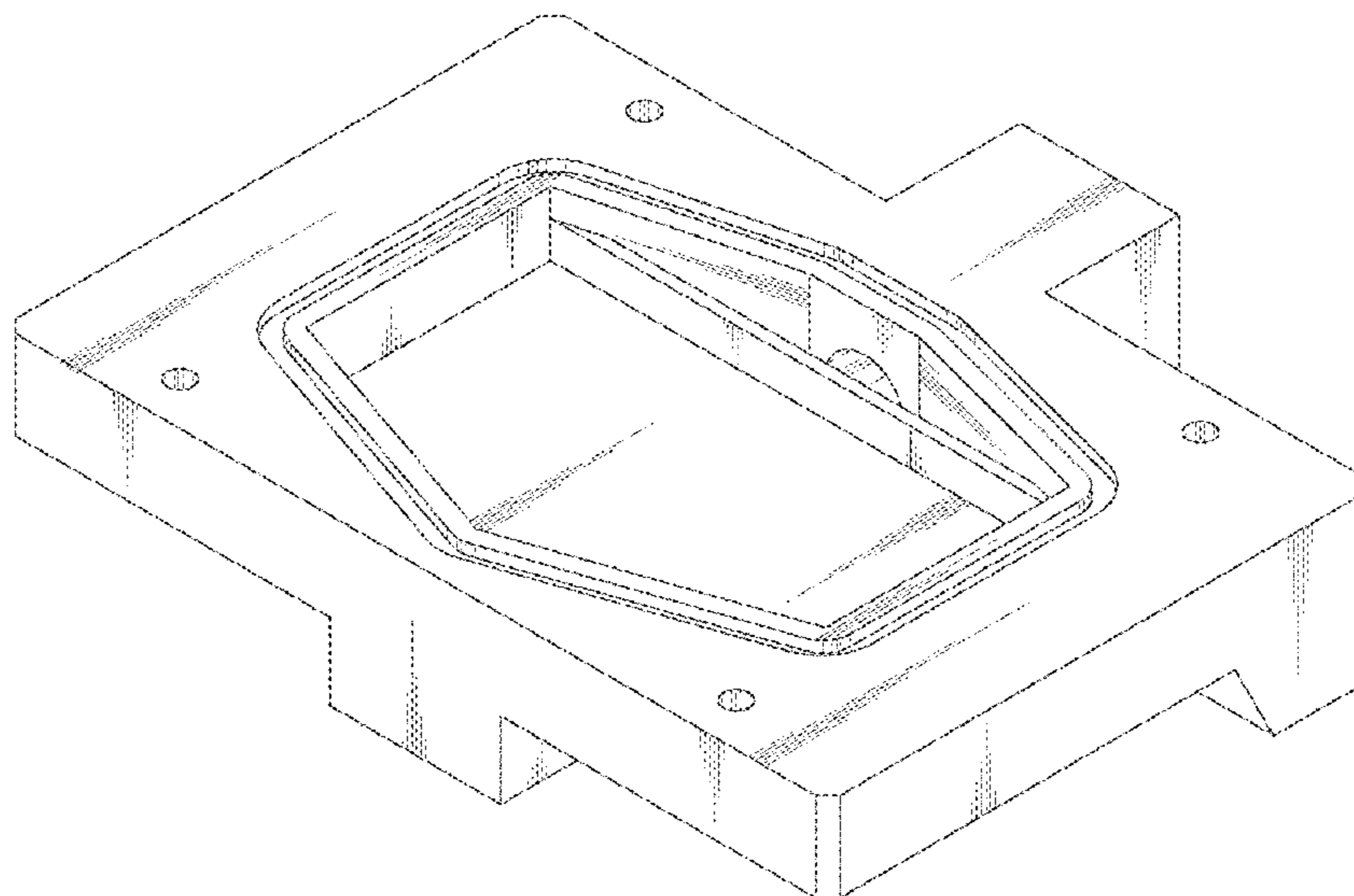


Fig. 1

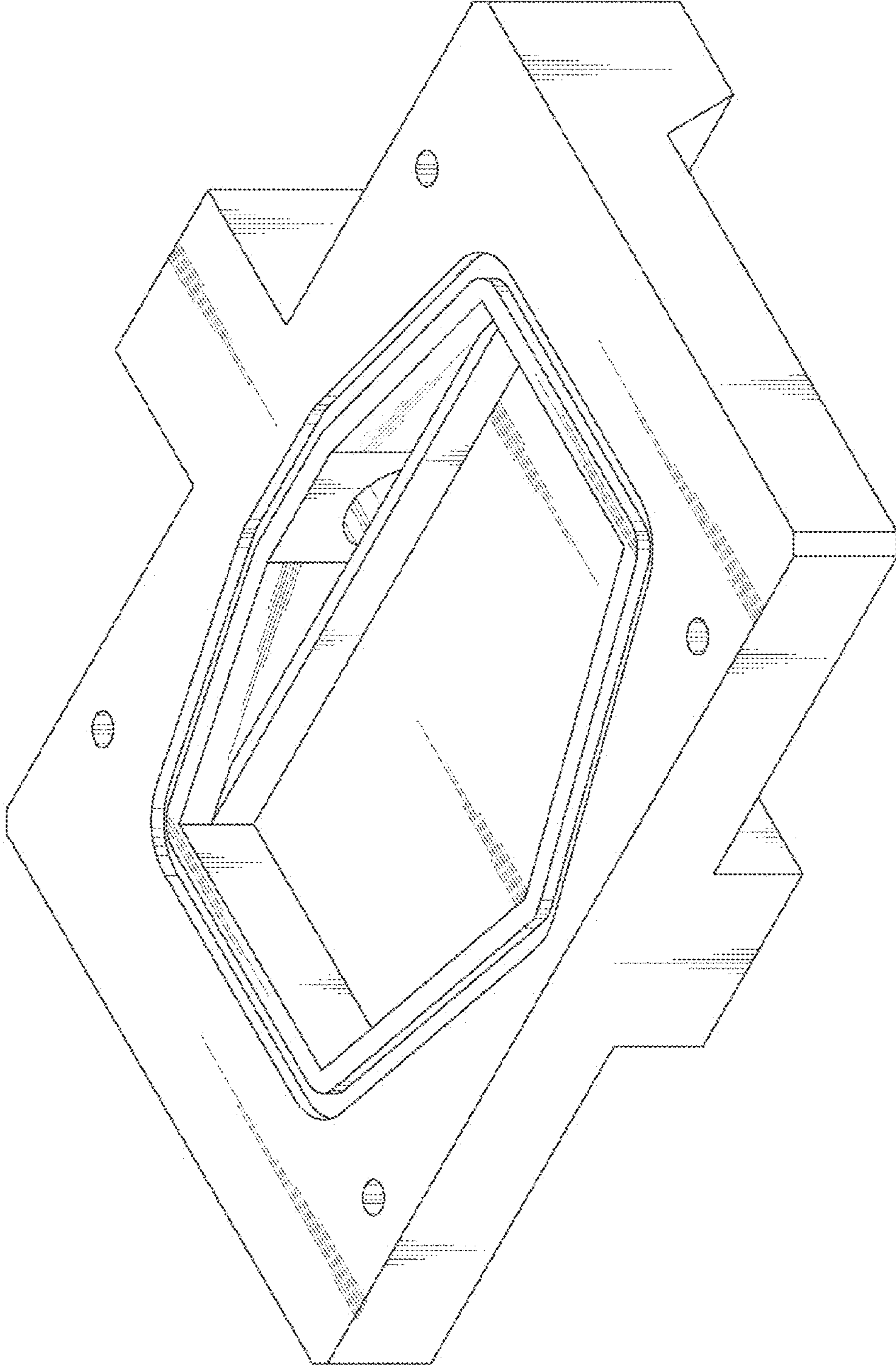


Fig. 2

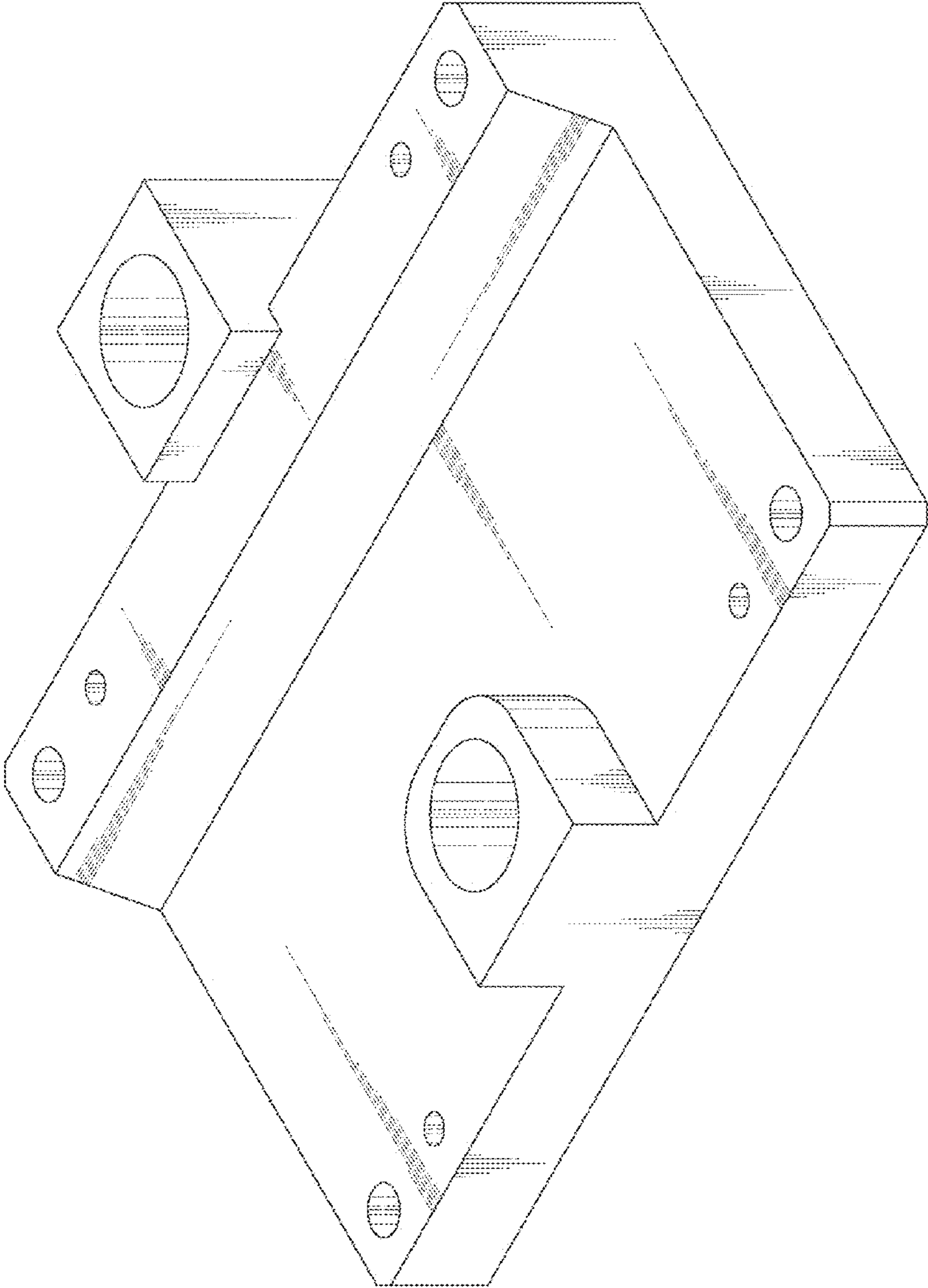


Fig. 3

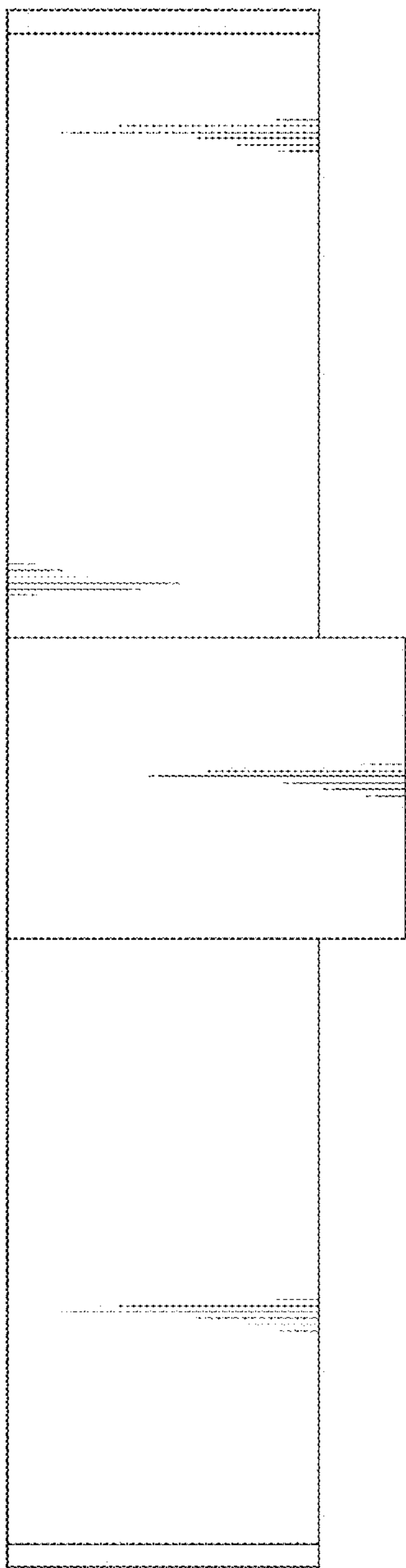
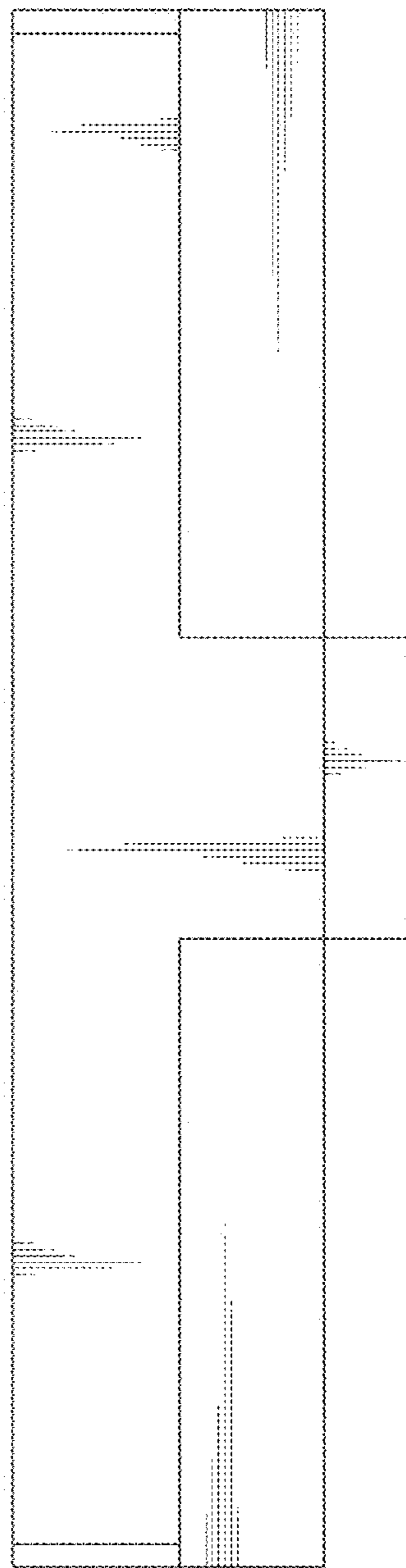
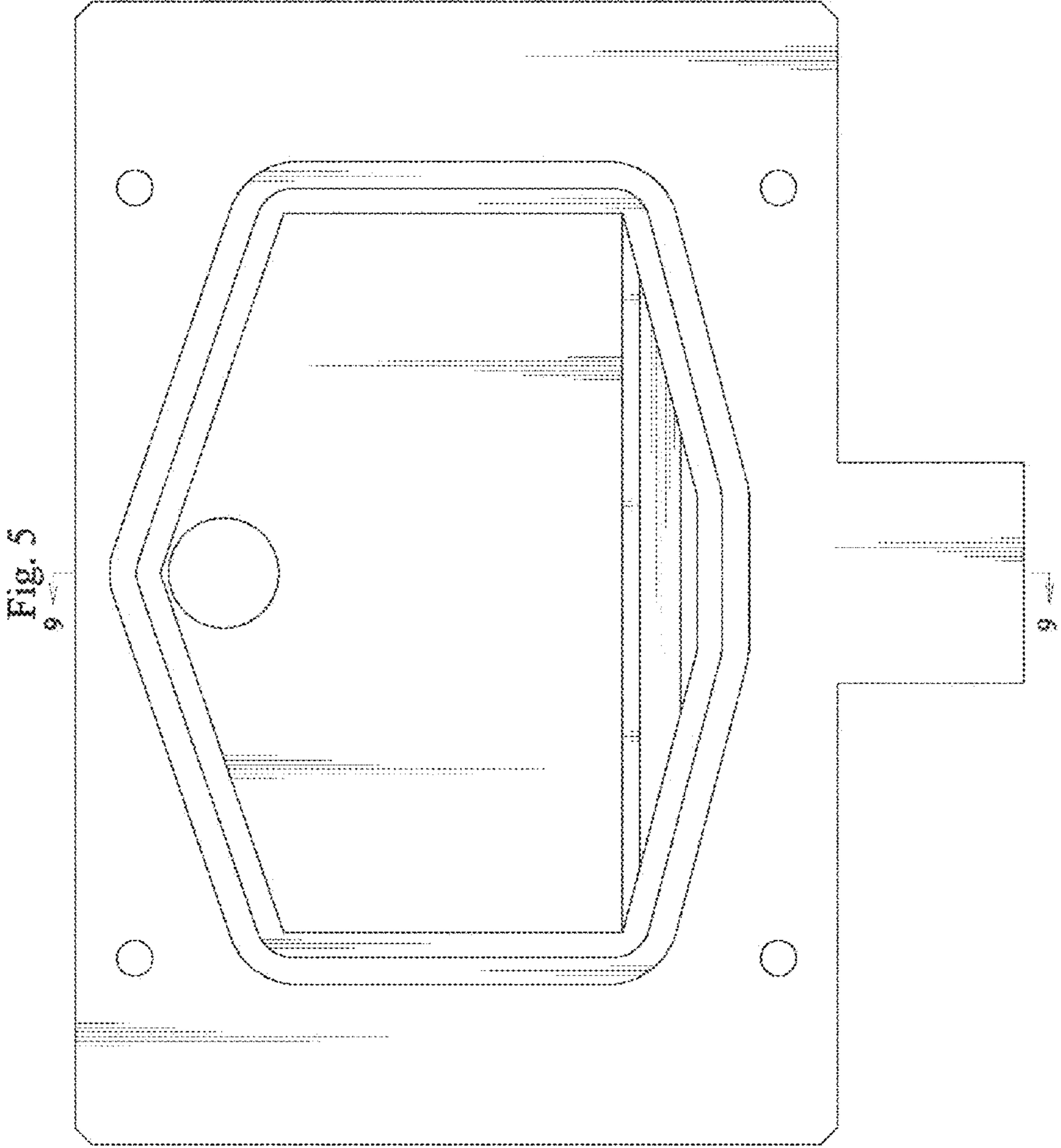


Fig. 4





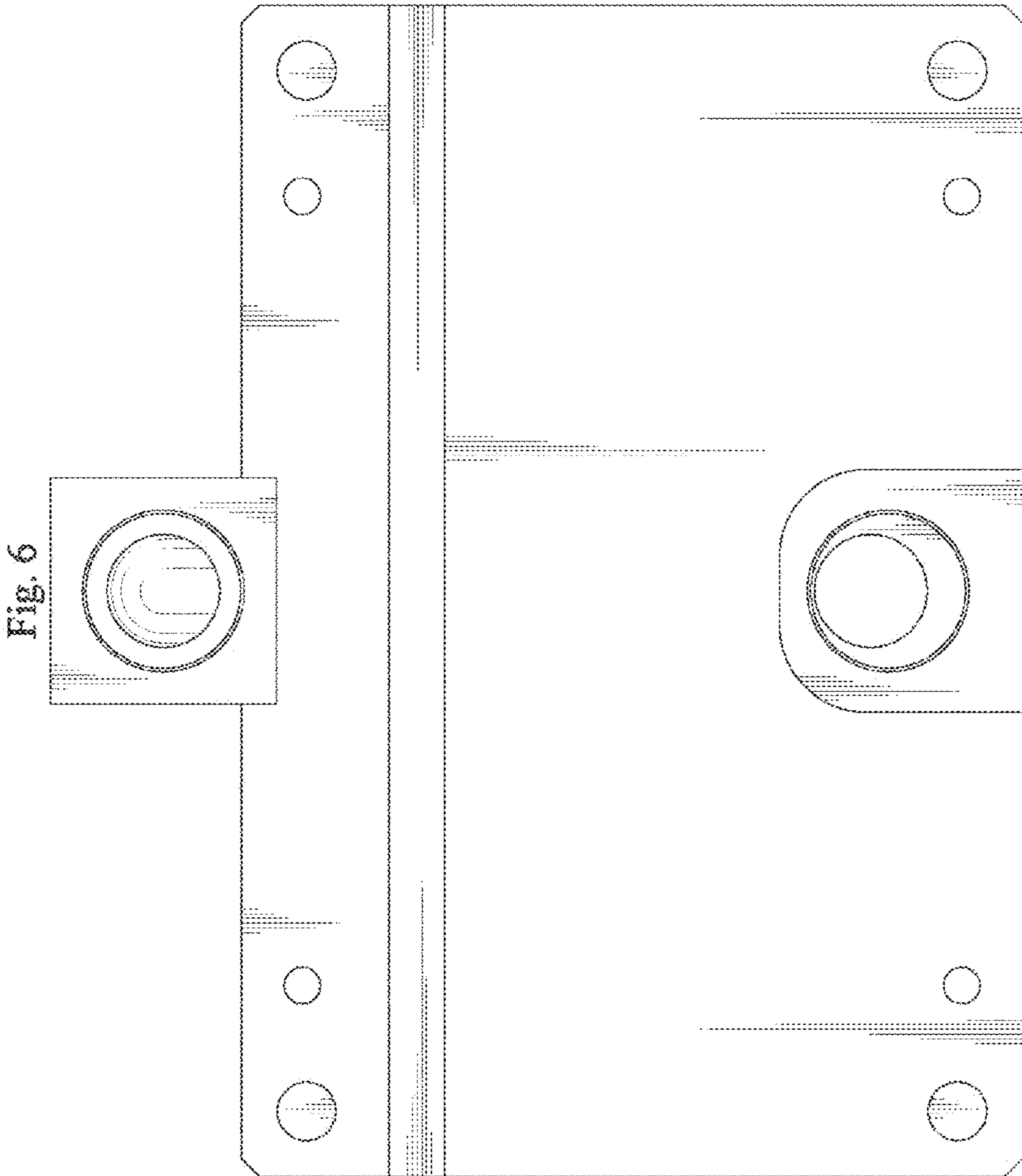


Fig. 7

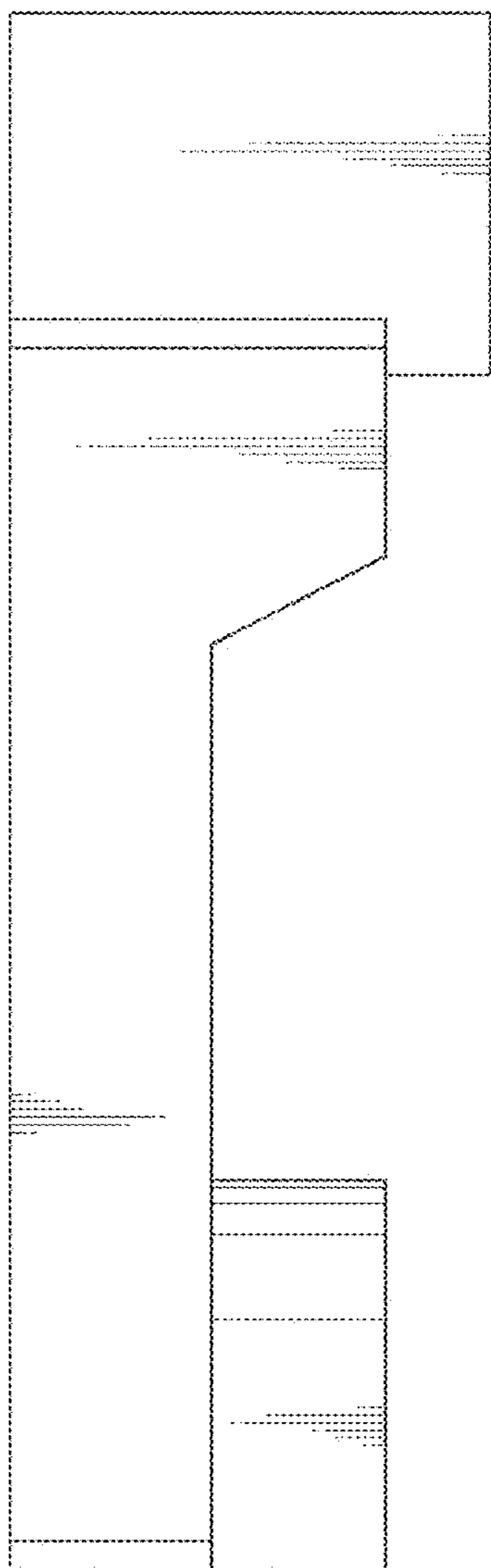


Fig. 8

